

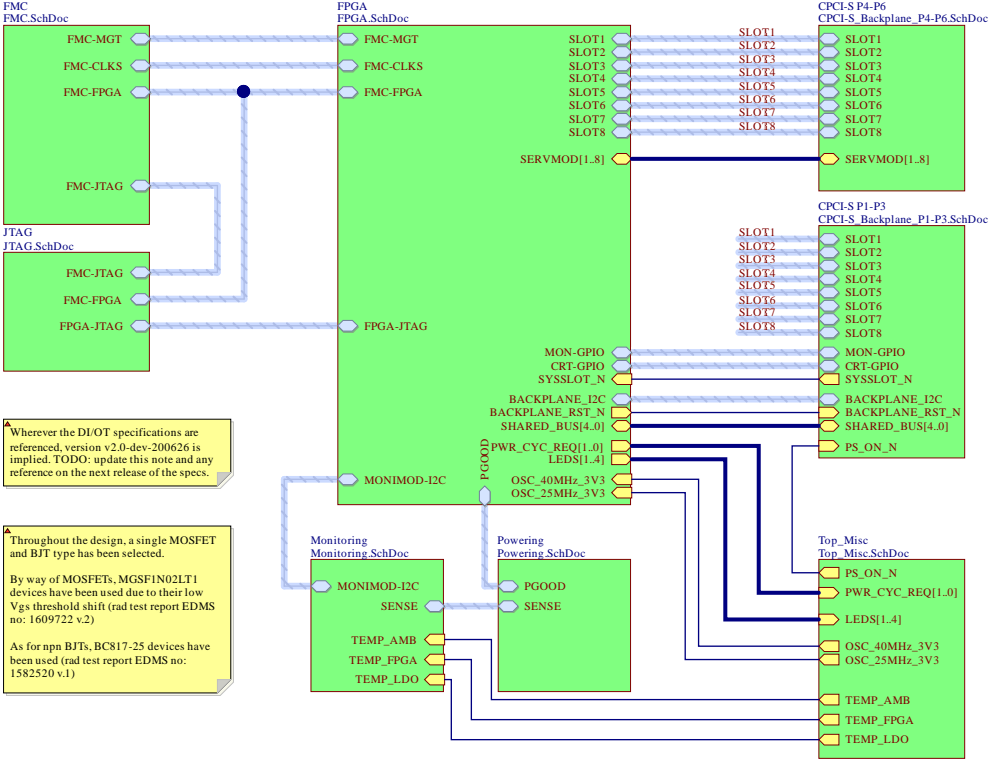
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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Wherever the DI/OT specifications are referenced, version v2.0-dev-200626 is implied. TODO: update this note and any reference on the next release of the specs.

Throughout the design, a single MOSFET and BJT type has been selected.

By way of MOSFETs, MGSF1N02LT1 devices have been used due to their low Vgs threshold shift (rad test report EDMS no: 1609722 v.2)

As for npn BJTs, BC817-25 devices have been used (rad test report EDMS no: 1582520 v.1)

Project/Equipment		DI/OT	
Document		Designer	C. Gentsos
		Drawn by	C. Gentsos
		Check by	*
		Last Mod.	C. Gentsos
		File	DIOT-sb-ig1_top.SchDoc
		Print Date	09/10/2020 15:28:47
		Sheet	1 of 18
		Size	A3
		Rev	*

BE/CO

DI/OT Rad-tol System Board

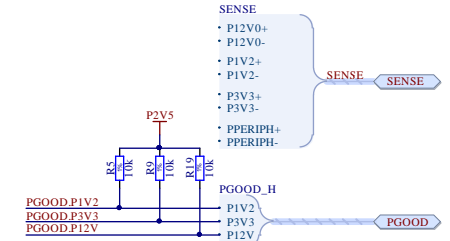
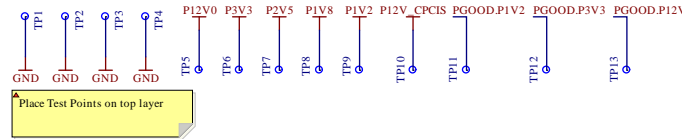
Top Level

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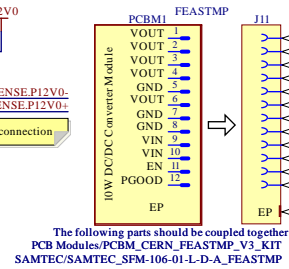
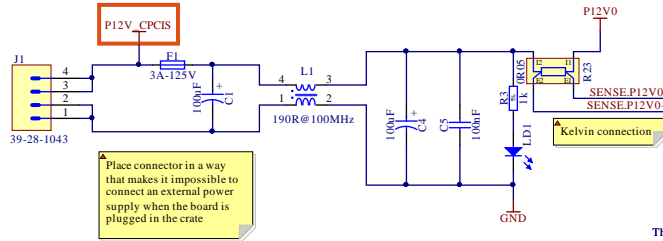
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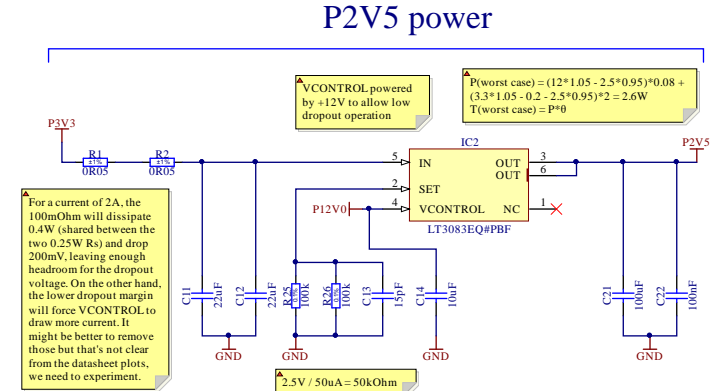
Test points



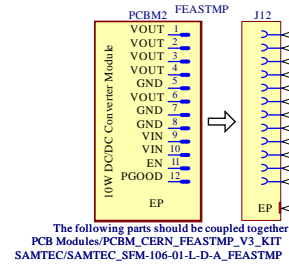
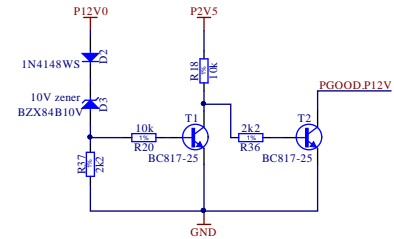
12V0 power cleanup



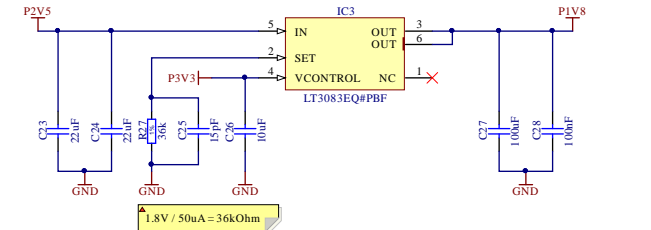
P1V2 power



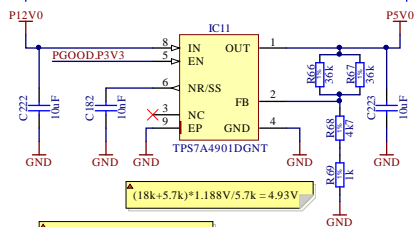
12V brownout detection



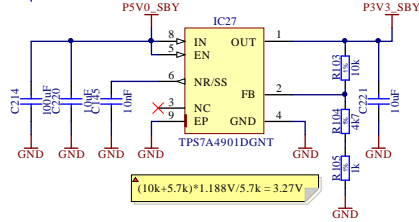
P3V3 power



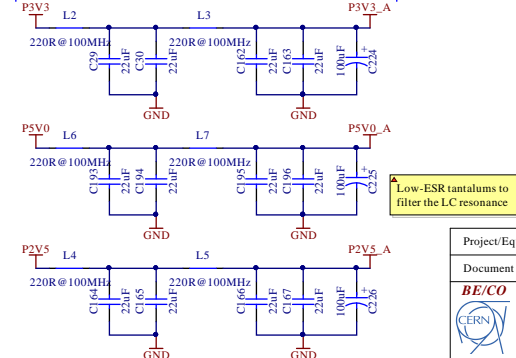
P5V0 power



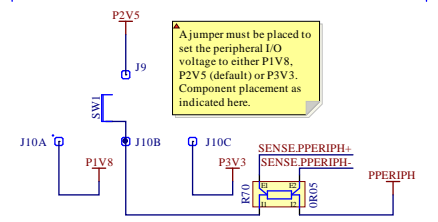
Always-on P3V3 power



Analog power filtering



Peripheral voltage selection



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		Print Date	09/10/2020 15:28:48	Sheet 2 of 18
				A3

DI/OT Rad-tol System Board Power

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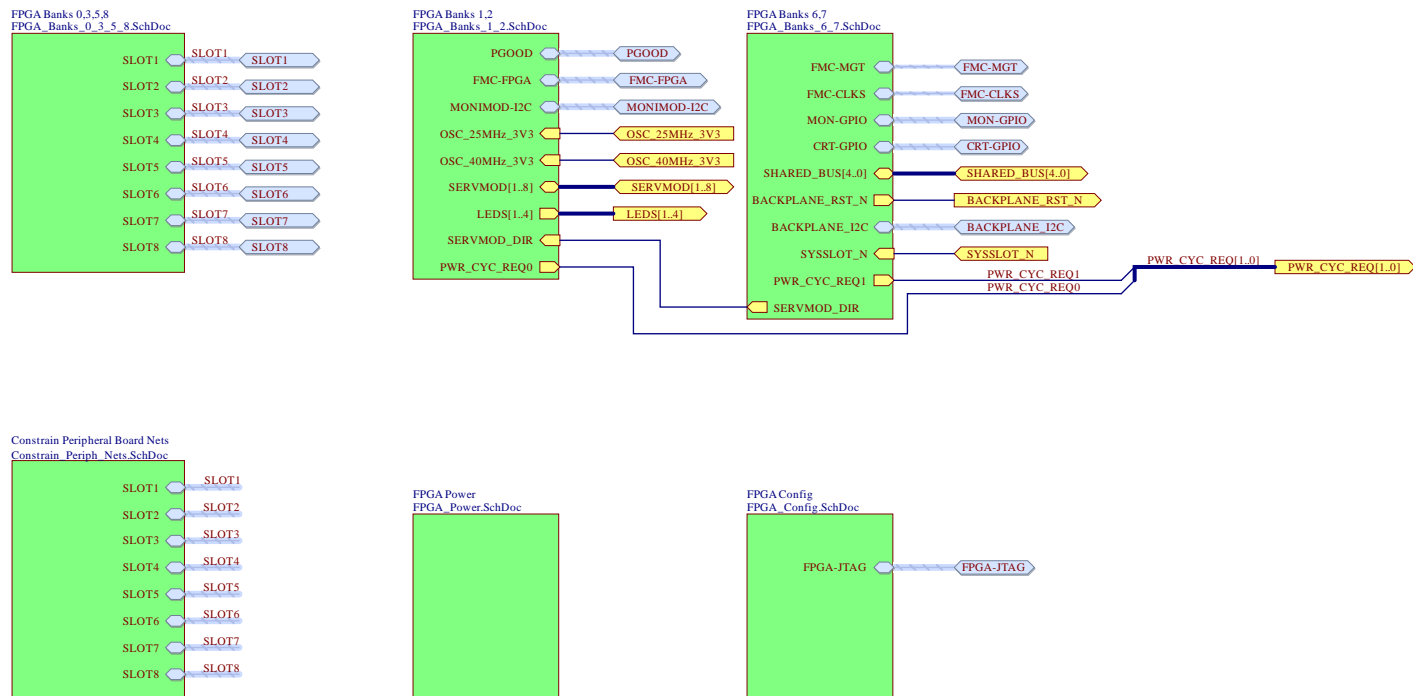
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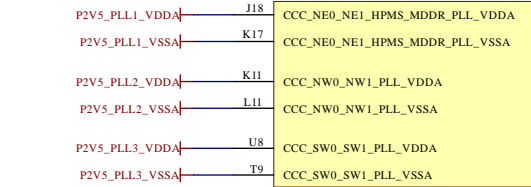
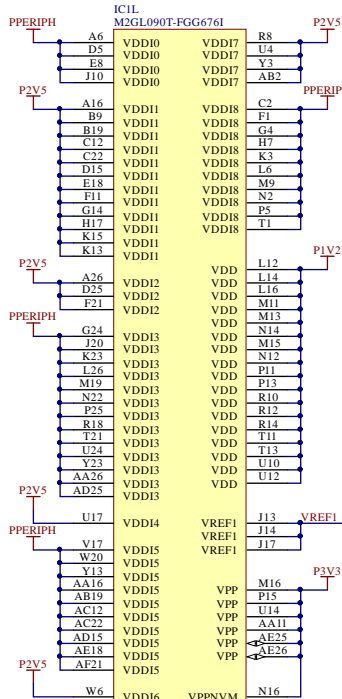
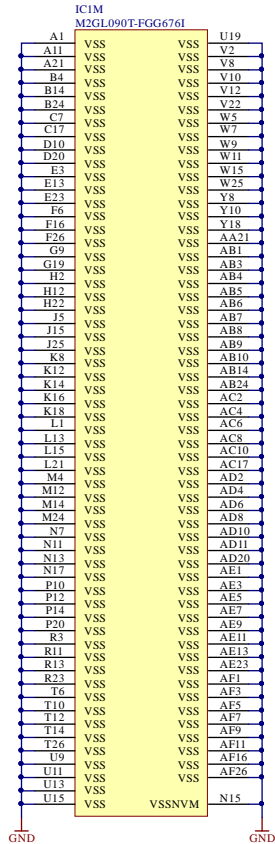
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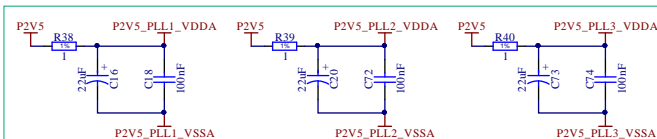
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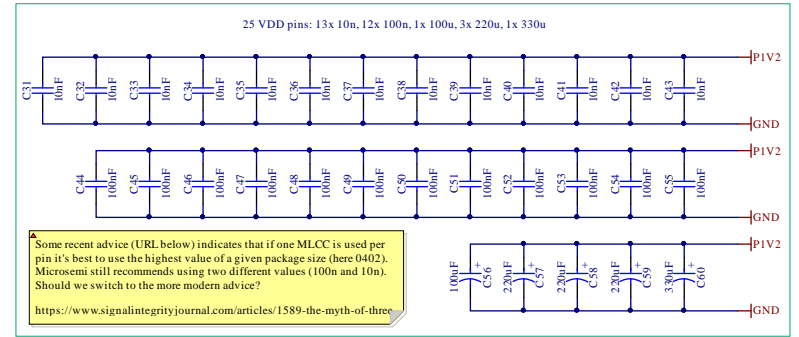


PLL power, 2.5V or 3.3V?
2.5V will be smoother due to the LDO so better jitter but is any of the two better for radiation?

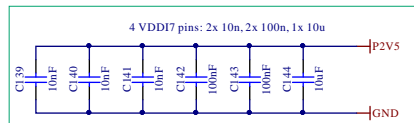
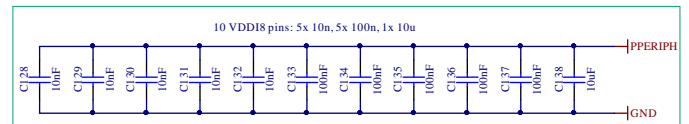
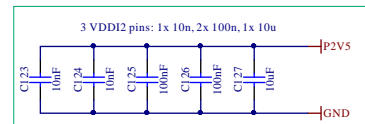
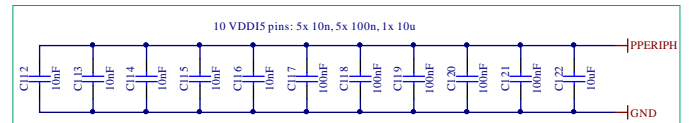
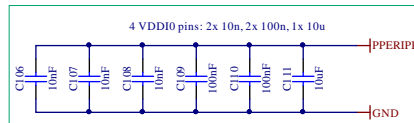
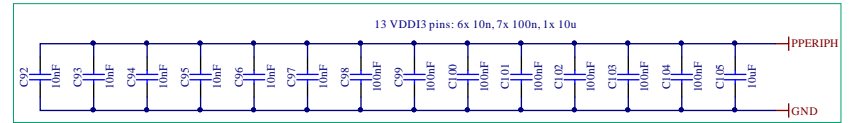
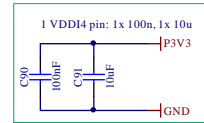
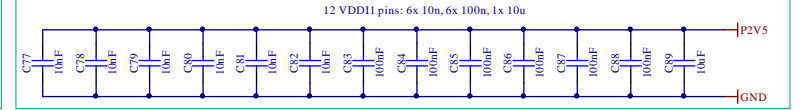
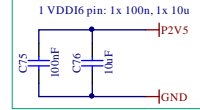
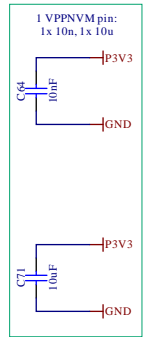
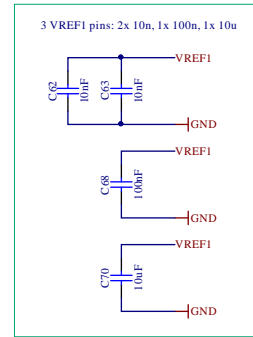
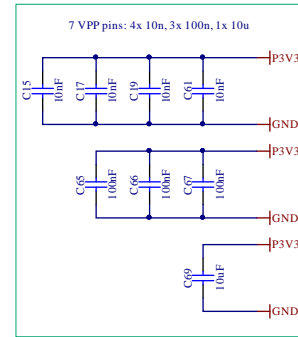
VPPNV must be shorted to VPP



Place the 0402 100nF caps close to the FPGA pins



Some recent advice (URL below) indicates that if one MLCC is used per pin it's best to use the highest value of a given package size (here 0402). Microsemi still recommends using two different values (100n and 10n). Should we switch to the more modern advice?
<https://www.signalintegrityjournal.com/articles/1589-the-myth-of-three>



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		File	FPGA_PowerSchDoc	
Print Date	09/10/2020 15:28:49	Sheet	4 of 18	
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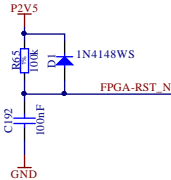
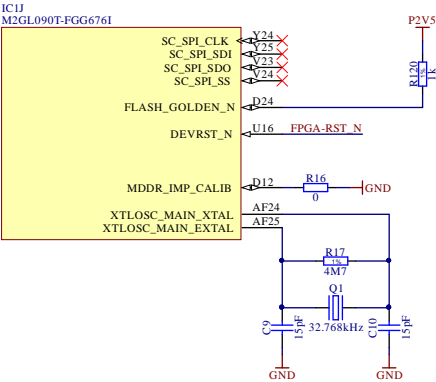
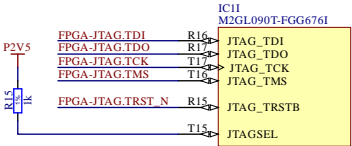
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Parts powered by 2.5V



The JTAG and configuration pins are referred to as Bank 4



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		File	FPGA_Config.SchDoc
		Print Date	09/10/2020 15:28:50
		Sheet	5 of 18
		Rev	A3
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BE/CO

DI/OT Rad-tol System Board
FPGA Configuration

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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

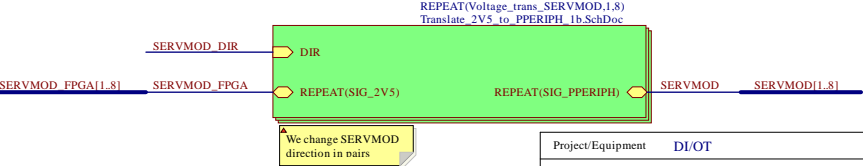
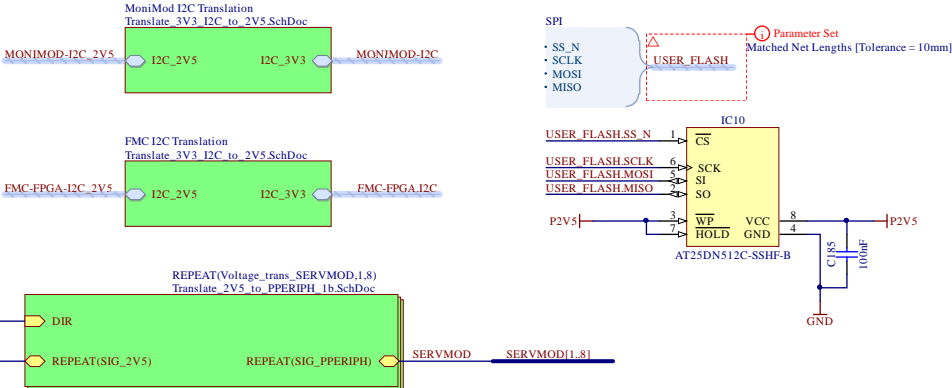
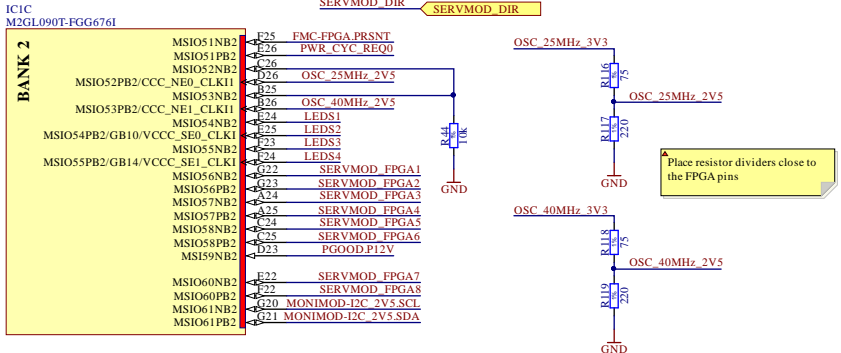
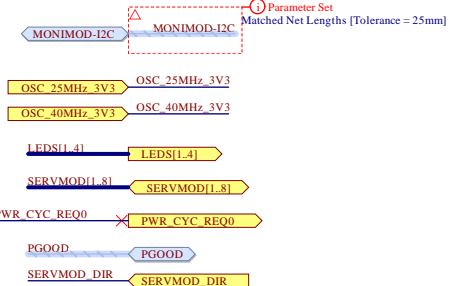
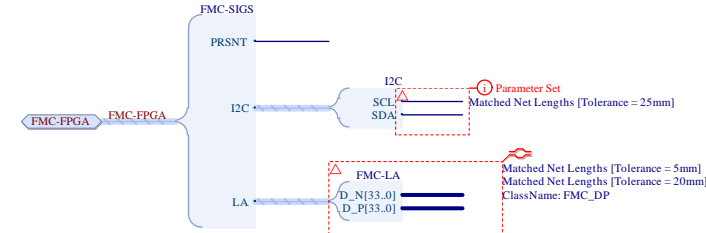
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Banks powered by 2.5V


Careful with pin swapping: the P nets of the differential pairs 0, 1, 17 and 18 are connected to clock-capable pins and can't be swapped with the other I/Os.

IC1B MZGL090T-FGG6761	
BANK 1	DDRIO62NB1/MDDR_ADDR15
	DDRIO62PB1/MDDR_ADDR14
	DDRIO63NB1/MDDR_ADDR15
	DDRIO63PB1/MDDR_ADDR12
	DDRIO64NB1/MDDR_ADDR11
	DDRIO64PB1/MDDR_ADDR10
	DDRIO65NB1/MDDR_ADDR9
	DDRIO65PB1/MDDR_ADDR8
	DDRIO66NB1/MDDR_ADDR7
	DDRIO66PB1/MDDR_ODT
	DDRIO67NB1/MDDR_ADDR6
	DDRIO67PB1/MDDR_ADDR5
	DDRIO68NB1/MDDR_ADDR4
	DDRIO68PB1/MDDR_ADDR3
	DDRIO69NB1/MDDR_ADDR2
	DDRIO69PB1/MDDR_ADDR1
	DDRIO70NB1/MDDR_ADDR0
	DDRIO70PB1/MDDR_BA2
	DDRIO71NB1/MDDR_BA1
	DDRIO71PB1/MDDR_BA0
	DDRIO72NB1/MDDR_CLK_N
	DDRIO72PB1/MDDR_CLK_N
	DDRIO73NB1/MDDR_CAS_N
	DDRIO73PB1/MDDR_RESET_N
	DDRIO74NB1/MDDR_CS_N
	DDRIO74PB1/MDDR_CKE
	DDRIO75NB1/MDDR_WE_N
	DDRIO75PB1/MDDR_RAS_N
	DDRIO76NB1/MDDR_DQ15
	DDRIO76PB1/CCC_NE1_CLK13/MDDR_DQ14
	DDRIO77NB1/MDDR_DQ13
	DDRIO77PB1/MDDR_DQ12/GB12/CCC_NE1_CLK12
	DDRIO78NB1/MDDR_DM_RDQS1
	DDRIO78PB1/MDDR_TMATCH_0_IN
	DDRIO79NB1/MDDR_DQS1_N
	DDRIO79PB1/MDDR_DQS1/GB8/CCC_NE0_CLK13
	DDRIO80NB1/MDDR_DQ10/CCC_NE0_CLK12
	DDRIO80PB1/MDDR_DQ10/CCC_NE0_CLK12
	DDRIO81NB1/MDDR_DQ9
	DDRIO81PB1/MDDR_DQ8
	DDRIO82NB1/MDDR_TMATCH_0_OUT
	DDRIO82PB1/MDDR_DQ7
	DDRIO83NB1/MDDR_DQ6
	DDRIO83PB1/MDDR_DQ5
	DDRIO84NB1/MDDR_DQ4
	DDRIO84PB1/MDDR_DM_RDQS0
	DDRIO85NB1/MDDR_DQS0_N
	DDRIO85PB1/MDDR_DQS0
	DDRIO86NB1/MDDR_DQ3
	DDRIO86PB1/MDDR_DQ2
	DDRIO87NB1/MDDR_DQ1
	DDRIO87PB1/MDDR_DQ0
	DDRIO88NB1
	DDRIO88PB1/CCC_NW1_CLK13
	DDRIO89NB1/MDDR_DQ_ECC0
	DDRIO89PB1/MDDR_DQ_ECC1
	DDRIO90NB1/MDDR_DM_RDQS_ECC
	DDRIO90PB1/MDDR_TMATCH_ECC_IN
	DDRIO91NB1/MDDR_DQS_ECC_N
	DDRIO91PB1/MDDR_DQS_ECC
	DDRIO92NB1/GB4/CCC_NW1_CLK12
	DDRIO92PB1/GB0/CCC_NW0_CLK13
	DDRIO93NB1/CCC_NW0_CLK12
	DDRIO93PB1/MDDR_TMATCH_ECC_OUT
	DDRIO94NB1
	DDRIO94PB1
	DDRIO95NB1
	DDRIO95PB1
	DDRIO96NB1
	DDRIO96PB1
	DDRIO97NB1
	DDRIO97PB1
	DDRIO98NB1
	DDRIO98PB1
	DDRIO99NB1
	DDRIO99PB1

C23	FMC-FPGA.LA.D_N14
C22	FMC-FPGA.LA.D_P14
C23	FMC-FPGA.LA.D_N15
C23	FMC-FPGA.LA.D_P15
C21	FMC-FPGA.LA.D_N2
C21	FMC-FPGA.LA.D_P2
C20	FMC-FPGA.LA.D_N3
C20	FMC-FPGA.LA.D_P3
C22	FMC-FPGA.LA.D_N4
C22	FMC-FPGA.LA.D_P4
C18	FMC-FPGA.LA.D_N5
C18	FMC-FPGA.LA.D_P5
C21	FMC-FPGA.LA.D_N6
C21	FMC-FPGA.LA.D_P6
C19	FMC-FPGA.LA.D_N7
C19	FMC-FPGA.LA.D_P7
C18	FMC-FPGA.LA.D_N8
C17	FMC-FPGA.LA.D_P8
C20	FMC-FPGA.LA.D_N9
C20	FMC-FPGA.LA.D_P9
C20	FMC-FPGA.LA.D_N10
C19	FMC-FPGA.LA.D_P10
C19	FMC-FPGA.LA.D_N11
C18	FMC-FPGA.LA.D_P11
C17	FMC-FPGA.LA.D_N12
C17	FMC-FPGA.LA.D_P12
C16	FMC-FPGA.LA.D_N13
C16	FMC-FPGA.LA.D_P13
C19	FMC-FPGA.LA.D_N1
C18	FMC-FPGA.LA.D_P1
C18	FMC-FPGA.LA.D_N0
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C14	FMC-FPGA.LA.D_P23
C14	FMC-FPGA.LA.D_N24
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C14	FMC-FPGA.LA.D_P31
C11	FMC-FPGA.LA.D_N32
C11	FMC-FPGA.LA.D_P32
C11	FMC-FPGA.LA.D_N33
C10	FMC-FPGA.LA.D_P33
C10	FMC-FPGA.LA.D_N34
C10	FMC-FPGA.LA.D_P34
C12	USER_FLASH_SS_N
C11	USER_FLASH_SCLK
C9	USER_FLASH_MOSI
C10	USER_FLASH_MISO
C10	PGOOD_P1V2
C9	PGOOD_P3V3



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BE/CO		Drawn by: C. Gentsos	
CERN		Check by: *	
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FPGA I/O Banks B1, B2		File: FPGA_Banks_1_2.SchDoc	
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B										B																			
C		<div>Maybe that's nit-picking but according to the datasheet, VCCB must be ramped-up with or after VCCA. If VCCB is set to 3V3 its ramp-up will come just slightly ahead of VCCA but not by much.</div> <div></div>								C																			
D										D																			
E		<div>Project/EquipmentDI/OT</div> <div>Document</div> <div><div>DI/OT Rad-tol System Board Voltage Translators</div><div>European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland</div></div> <div><table><tr><td>Designer</td><td>C. Gentsos</td><td></td></tr><tr><td>Drawn by</td><td>C. Gentsos</td><td>16/09/2020</td></tr><tr><td>Check by</td><td>*</td><td></td></tr><tr><td>Last Mod.</td><td>C. Gentsos</td><td>09/10/2020</td></tr><tr><td>File</td><td>Translate_2V5_to_PPERIPH_1b.SchDoc</td><td></td></tr><tr><td>Print Date</td><td>09/10/2020 15:28:53</td><td>Sheet 8 of 18</td></tr></table><div>EDA-XXXXX-VX-X</div><div><div>REV</div><div>A3</div><div>*</div></div></div>								Designer	C. Gentsos		Drawn by	C. Gentsos	16/09/2020	Check by	*		Last Mod.	C. Gentsos	09/10/2020	File	Translate_2V5_to_PPERIPH_1b.SchDoc		Print Date	09/10/2020 15:28:53	Sheet 8 of 18	E	
Designer	C. Gentsos																												
Drawn by	C. Gentsos	16/09/2020																											
Check by	*																												
Last Mod.	C. Gentsos	09/10/2020																											
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1		2		3		4		5																					

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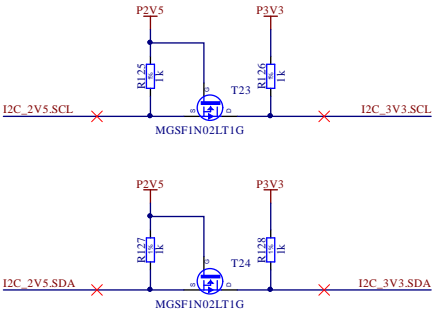
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Document		Designer	C. Gentsos
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		Check by	*
		Last Mod.	C. Gentsos
		File	Translate_3V3_I2C_to_2V5_SchDoc
		Print Date	09/10/2020 15:28:53
		Sheet	9 of 18
		REV	A3
		*	*



DI/OT Rad-tol System Board

I2C Voltage Translators

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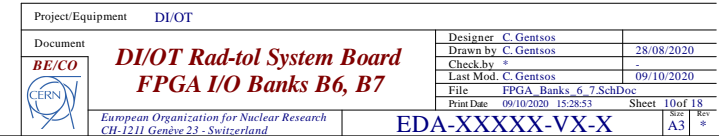
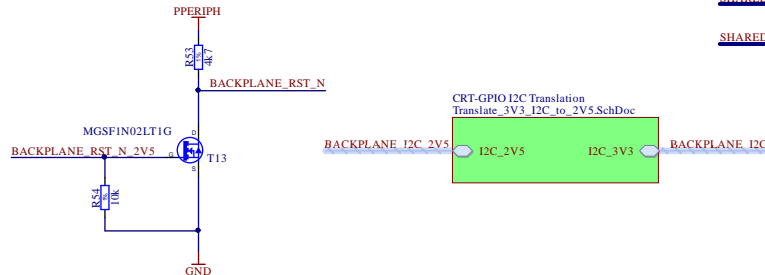
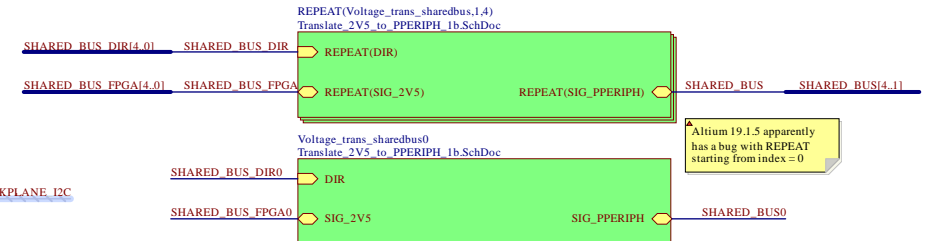
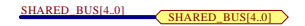
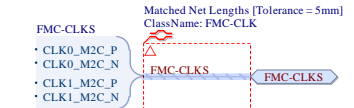
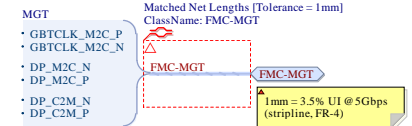
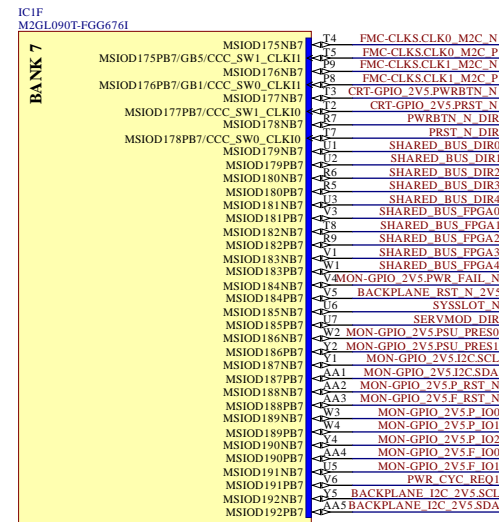
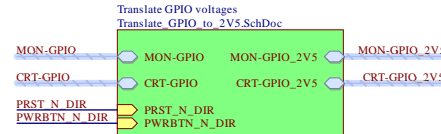
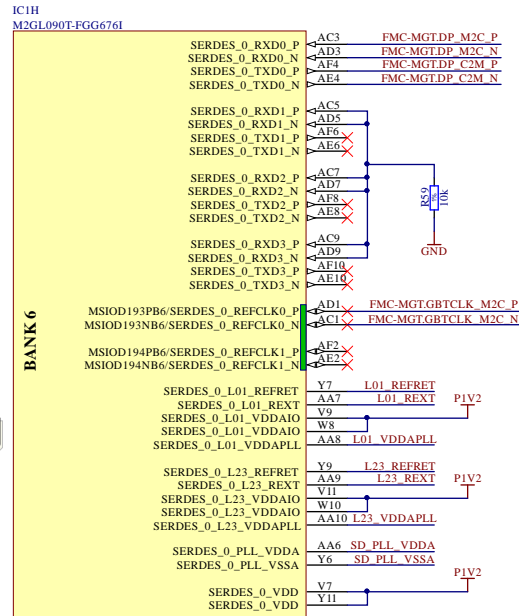
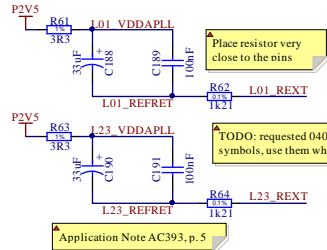
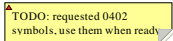
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Banks powered by 2.5V



Document
BE/CO
CERN

DI/OT Rad-tol System Board FPGA I/O Banks B6, B7

Designer	C. Gentsos	
Drawn by	C. Gentsos	28/08/2020
Check by	*	-
Last Mod.	C. Gentsos	09/10/2020
File	FPGA_Banks_6_7.SchDoc	
Print Date	09/10/2020 15:28:53	Sheet 10 of 18

0A-XXXXX-VX-X	Size A3	Rev *
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EDA-XXXXX-VX-X

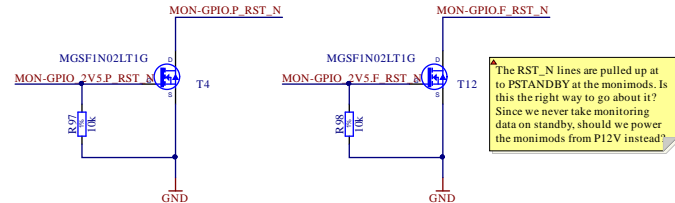
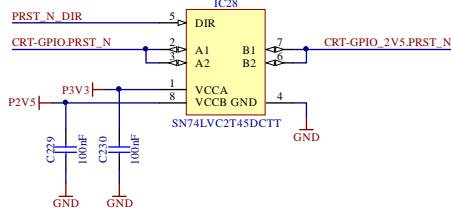
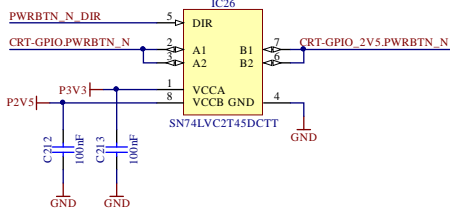
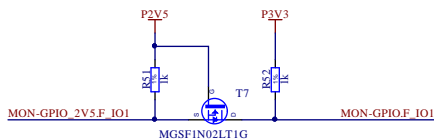
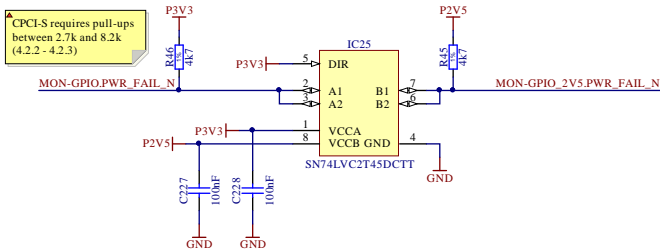
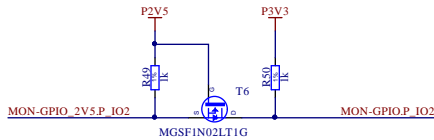
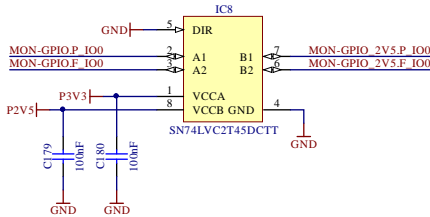
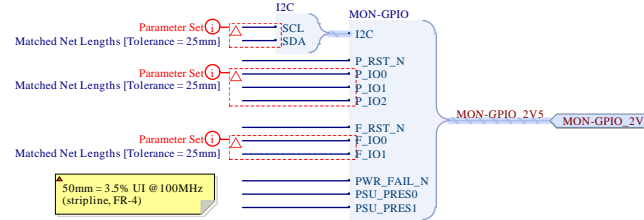
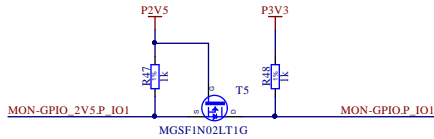
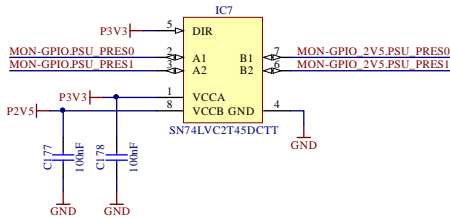
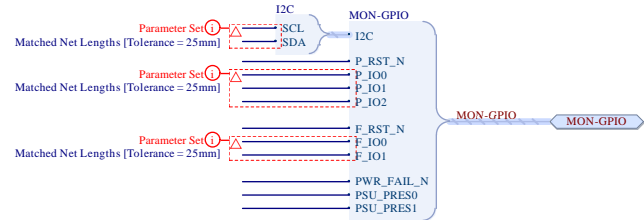
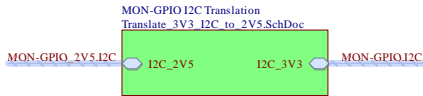
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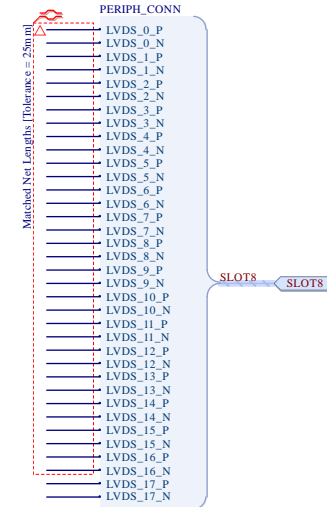
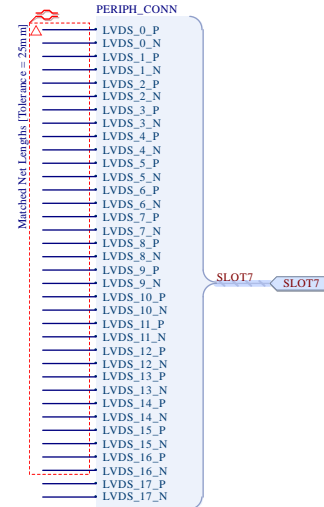
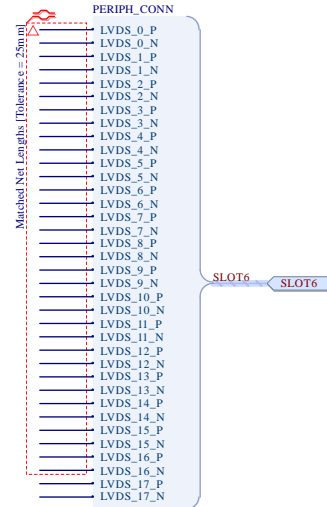
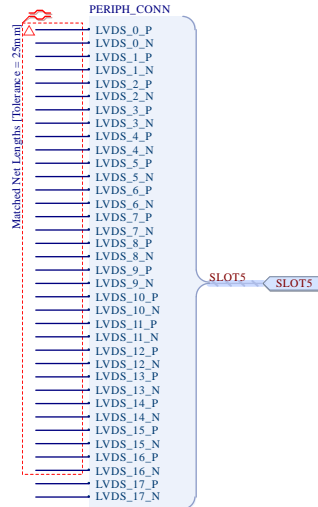
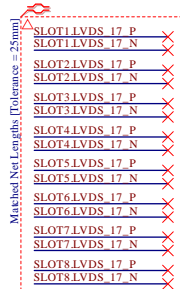
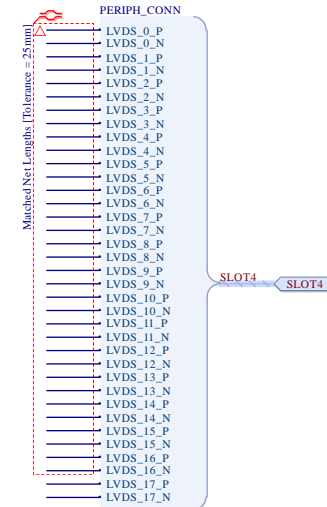
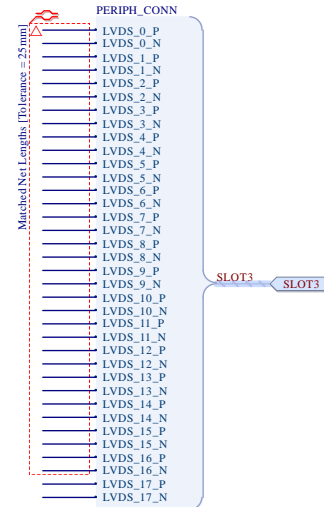
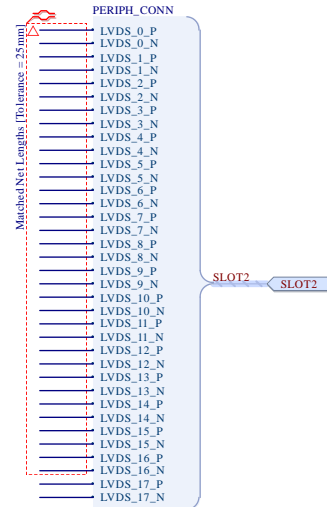
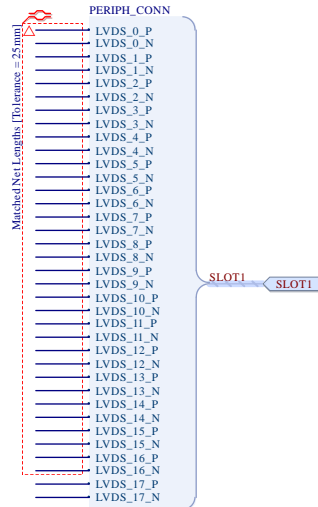
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Project/Equipment	DI/OT	Designer	C. Gentsos	23/09/2020
Document	BE/CO	Drawn by	C. Gentsos	09/10/2020
		Check by	*	09/10/2020
		Last Mod.	C. Gentsos	09/10/2020
		File	Translate_GPIO_to_2V5.SchDoc	11 of 18
		Print Date	09/10/2020 15:28:54	Sheet
				11 of 18
				A3



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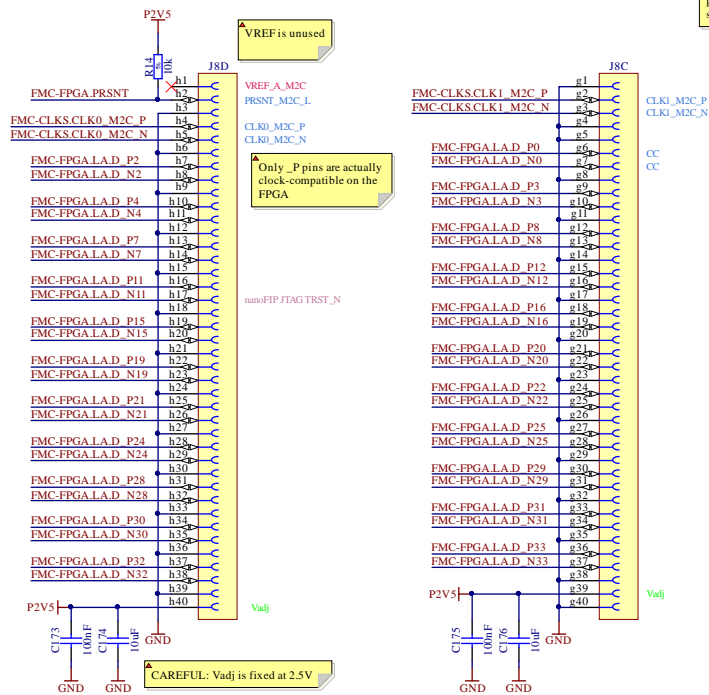
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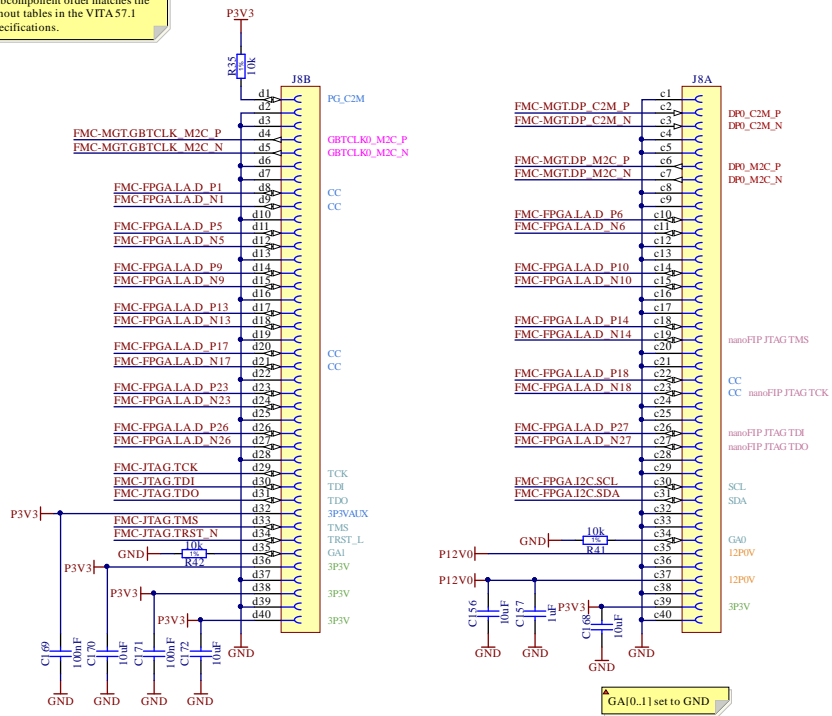
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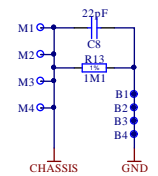
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Subcomponent order matches the pinout tables in the VITA 57.1 specifications.



Front panel and FMC slot spacers



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
		Drawn by C. Gentsos	
		Check by *	
		Last Mod. C. Gentsos	
		File FMC_SchDoc	
Print Date		09/10/2020 15:28:58	
		Sheet 15 of 18	
		A3	

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CERN
DI/OT Rad-tol System Board
FMC
European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

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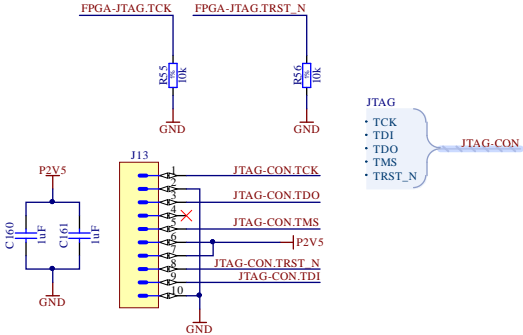
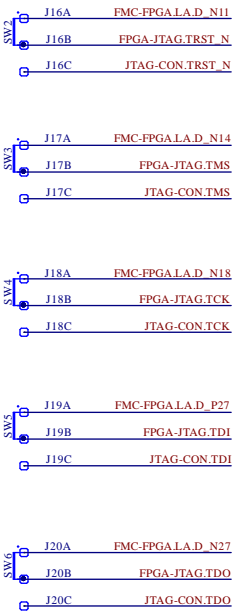
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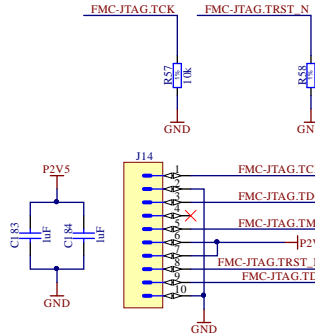
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In the Igloo2 evaluation board they use HTST-105-01-L-DV-A but there doesn't seem to be any difference.



Don't confuse this with the nanoFIP JTAG, this is just to provide an easily accessible JTAG connector to program the FMC card

Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
		Drawn by C. Gentsos	
		Check by *	
		Last Mod. C. Gentsos	
		File JTAG SchDoc	
		Print Date 09/10/2020 15:28:59	
		Sheet 16 of 18	
		Size A3	
		REV *	

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DI/OT Rad-tol System Board

JTAG Chains

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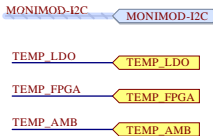
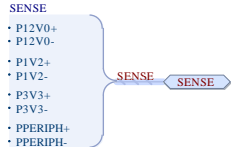
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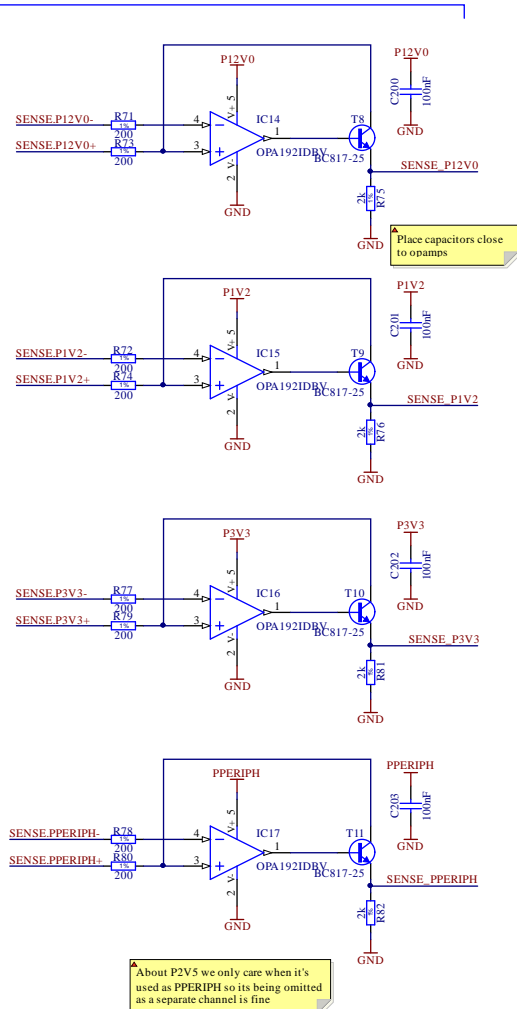
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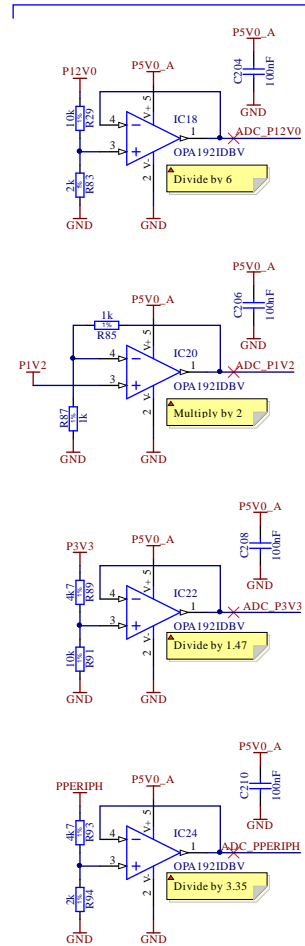
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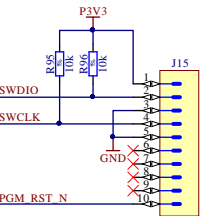
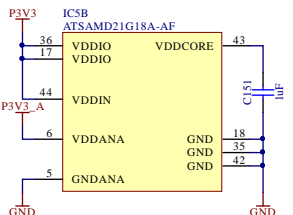
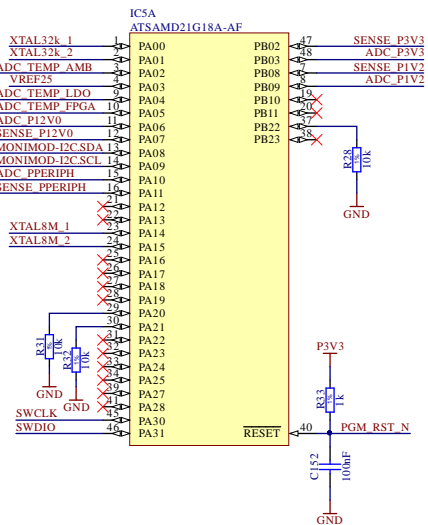
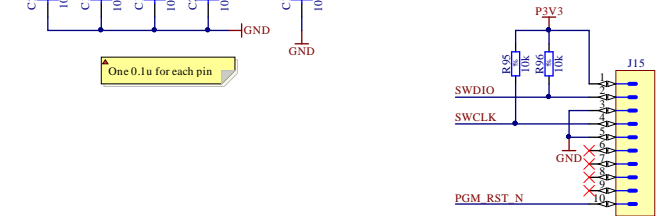
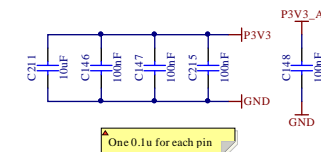
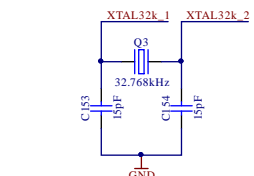
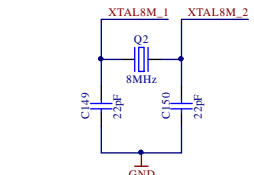
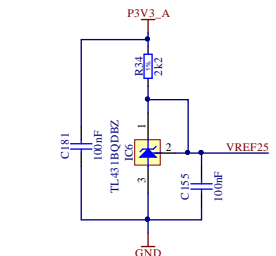
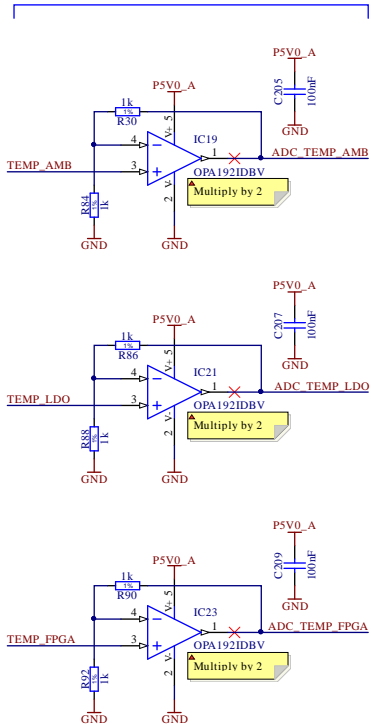
Current sense



Voltage div. and buffers



Temp. sensor amps



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
CERN		Check by *	
		Last Mod. C. Gentsos	
		File Monitoring_SchDoc	
		Print Date 09/10/2020 15:28:50	
		Sheet 17 of 18	
		A3	

DI/OT Rad-tol System Board Monitoring

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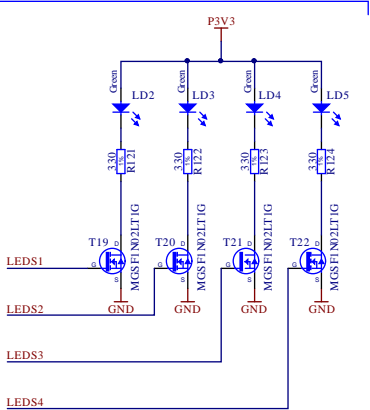
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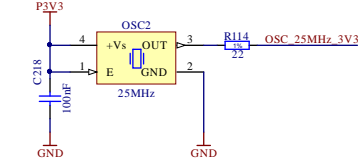
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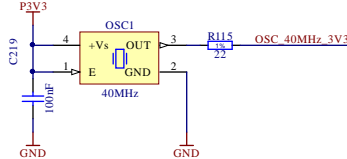
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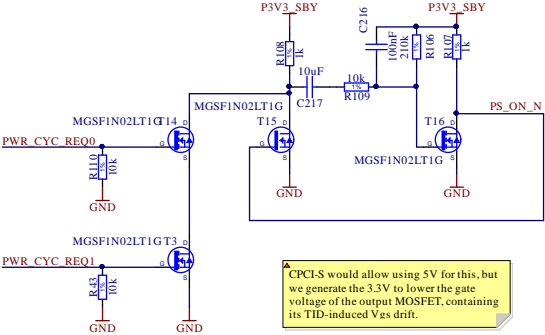
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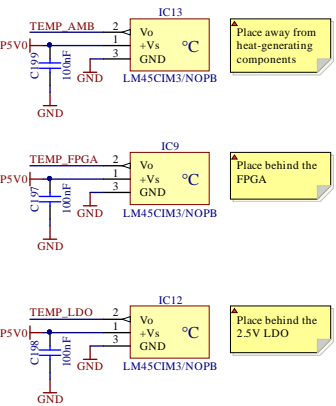
40MHz oscillator



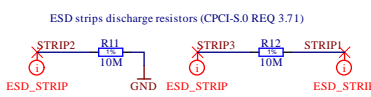
Power cycle pulse generator



Temp sensors



ESD Protection



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
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DI/OT Rad-tol System Board		Last Mod. C. Gentsos	
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